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Form 1449 (Modified) 12/22/2006 Information Disclosure Statement By Applicant (Use Several Sheets if Necessary)	Atty Docket No. LAM1P177/P1139 Applicant: KANG et al. Filing Date August 26, 2003	Application No.: 10/648,953 Group 2823
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U.S. Patent Documents

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub-class	Filing Date
JM	A1.	2005/0164479A1	07/28/05	Perng et al.	438	591	01/27/04
	A2.						
	A3.						
	A4.						
	A5.						
	A6.						
	A7.						
	A8.						
	A9.						
	A10.						

Foreign Patent or Published Foreign Patent Application

Examiner Initial	No.	Document No.	Publication Date	Country or Patent Office	Class	Sub-class	Translation	
							Yes	No
	B1.							
	B2.							
	B3.							
	B4.							
	B5.							

Other Documents

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
JM	C1.	Eric Eisenbraun et al., "Atomic Layer Deposition (ALD) of Tantalum-based Materials for Zero Thickness Copper Barrier Applications", Proceedings of IEEE (2001), pages 207-209.
	C2.	
	C3.	
	C4.	

Examiner /Julio Maldonado/ (01/06/2007)	Date Considered 01/06/2007
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Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.